

06-29-2005

FORM PTO-1595

(Rev. 10/02)

R

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office**Docket No.: 043890-0748****103030160**

To the Honorable Commissioner for Patents and Trademarks: Please record the attached original documents or copy thereto:

1. Name of Conveying Party(ies):

Tadahiko SAKAI and Tadashi MAEDA

2. Name and address of receiving party(ies):

Name: MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD.

Address: 1006, Oaza Kadoma,
Kadoma-shi, Osaka 571-8501 JAPANAdditional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of Conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

Execution Date: June 14, 2005

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If the document is being filed together with a new application, the execution date of the application is: June 14, 2005

A. Patent Application No(s).

B. Patent No(s).

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: MCDERMOTT WILL & EMERY LLP

Internal Address:

Street Address: 600 13th Street, N.W.

City: Washington State: D. C. Zip: 20005-3096

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41)

\$40.00

☐ Enclosed☒ Authorized to be charged to deposit account

8. Deposit account number:

500417

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Michael E. Fogarty, Registration No. 36,139

June 22, 2005

Name and Registration No. of Person Signing

Signature

Date

Total number of pages including cover sheet:

3

OMB No. 0651-0027 (exp. 6/30/2005)

06/29/2005 GTOW11 00000081 500417 11157921
 01 FC:6021 40.00 DA

PATENT
REEL: 016719 FRAME: 0936

Docket No.:

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

(1) <u>Tadahiko SAKAI</u>	(4) _____
(2) <u>Tadashi MAEDA</u>	(5) _____
(3) _____	(6) _____

who have made a certain new and useful invention, hereby sell, assign and transfer unto

MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD.

1006, Oaza Kadoma,

Kadoma-shi,

Osaka 571-8501 Japan

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

METHOD OF SOLDERING ELECTRONIC COMPONENT HAVING SOLDER BUMPS

TO SUBSTRATE

(a) for which an application for United States Letters Patent was filed on _____, and identified by United States Serial No. _____; or

(b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorize and request the United States Commissioner for Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the dates indicated aside our signatures:

INVENTORS		DATE SIGNED
1)	<u>Tadahiko Sakai</u> Name: Tadahiko SAKAI	June 14, 2005
2)	<u>Tadashi Maeda</u> Name: Tadashi MAEDA	June 14, 2005
3)	Name: _____	_____
4)	Name: _____	_____
5)	Name: _____	_____
6)	Name: _____	_____